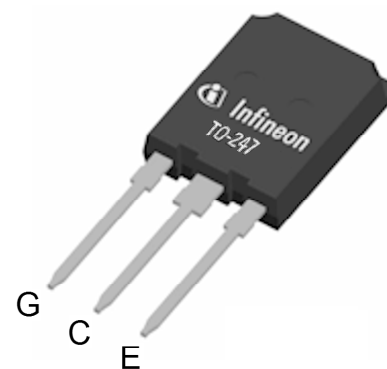
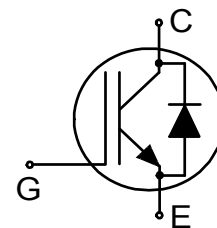


## TRENCHSTOP™ series

Low Loss DuoPack : IGBT in TRENCHSTOP™ and Fieldstop technology with soft, fast recovery anti-parallel Emitter Controlled diode

### Features:

- Very low  $V_{CE(sat)}$  1.5V (typ.)
- Maximum junction temperature 175°C
- Short circuit withstand time 5µs
- TRENCHSTOP™ and Fieldstop technology for 600V applications offers:
  - very tight parameter distribution
  - high ruggedness, temperature stable behavior
  - high switching speed
- Positive temperature coefficient in  $V_{CE(sat)}$
- Low EMI
- Low gate charge  $Q_G$
- Increased current capability
- Green package
- Very soft, fast recovery anti-parallel Emitter Controlled HE diode



### Applications:

- General purpose inverters
- Uninterruptible power supplies
- Motor drives
- Medium to low switching frequency power converters



### Key Performance and Package Parameters

Type	$V_{CE}$	$I_C$	$V_{CE(sat)}$ , $T_{vj}=25^\circ\text{C}$	$T_{vjmax}$	Marking	Package
IKQ100N60T	600V	100A	1.5V	175°C	K100T60	PG-TO247-3-46

## Table of Contents

Description .....	1
Table of Contents .....	2
Maximum Ratings .....	3
Thermal Resistance .....	3
Electrical Characteristics .....	4
Electrical Characteristics Diagrams .....	6
Package Drawing .....	13
Testing Conditions .....	14
Revision History .....	15
Disclaimer .....	16

## TRENCHSTOP™ series

## Maximum Ratings

For optimum lifetime and reliability, Infineon recommends operating conditions that do not exceed 80% of the maximum ratings stated in this datasheet.

Parameter	Symbol	Value	Unit
Collector-emitter voltage, $T_{vj} \geq 25^{\circ}\text{C}$	$V_{CE}$	600	V
DC collector current, limited by $T_{vjmax}$ $T_c = 25^{\circ}\text{C}$ value limited by bondwire $T_c = 130^{\circ}\text{C}$	$I_C$	160.0 100.0	A
Pulsed collector current, $t_p$ limited by $T_{vjmax}$	$I_{Cpuls}$	400.0	A
Turn off safe operating area $V_{CE} \leq 600\text{V}$ , $T_{vj} \leq 175^{\circ}\text{C}$ , $t_p = 1\mu\text{s}$	-	400.0	A
Diode forward current, limited by $T_{vjmax}$ $T_c = 25^{\circ}\text{C}$ value limited by bondwire $T_c = 117^{\circ}\text{C}$	$I_F$	160.0 100.0	A
Diode pulsed current, $t_p$ limited by $T_{vjmax}$	$I_{Fpuls}$	400.0	A
Gate-emitter voltage	$V_{GE}$	$\pm 20$	V
Short circuit withstand time $V_{GE} = 15.0\text{V}$ , $V_{CC} \leq 400\text{V}$ Allowed number of short circuits < 1000 Time between short circuits: $\geq 1.0\text{s}$ $T_{vj} = 150^{\circ}\text{C}$	$t_{SC}$	5	$\mu\text{s}$
Power dissipation $T_c = 25^{\circ}\text{C}$	$P_{tot}$	714.0	W
Operating junction temperature	$T_{vj}$	-40...+175	$^{\circ}\text{C}$
Storage temperature	$T_{stg}$	-55...+150	$^{\circ}\text{C}$
Soldering temperature, <sup>1)</sup> wave soldering 1.6mm (0.063in.) from case for 10s		260	$^{\circ}\text{C}$

## Thermal Resistance

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
<b>R<sub>th</sub> Characteristics</b>						
IGBT thermal resistance, <sup>2)</sup> junction - case	$R_{th(j-c)}$		-	-	0.21	K/W
Diode thermal resistance, <sup>2)</sup> junction - case	$R_{th(j-c)}$		-	-	0.35	K/W
Thermal resistance junction - ambient	$R_{th(j-a)}$		-	-	40	K/W

<sup>1)</sup> Package not recommended for surface mount application

<sup>2)</sup> Thermal resistance of thermal grease  $R_{th(c-s)}$  (case to heat sink) of more than 0.1K/W not included.

## TRENCHSTOP™ series

Electrical Characteristic, at  $T_{vj} = 25^{\circ}\text{C}$ , unless otherwise specified

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
<b>Static Characteristic</b>						
Collector-emitter breakdown voltage	$V_{(BR)CES}$	$V_{GE} = 0\text{V}, I_C = 0.20\text{mA}$	600	-	-	V
Collector-emitter saturation voltage	$V_{CEsat}$	$V_{GE} = 15.0\text{V}, I_C = 100.0\text{A}$ $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 175^{\circ}\text{C}$	- -	1.50 1.90	2.00 -	V
Diode forward voltage	$V_F$	$V_{GE} = 0\text{V}, I_F = 100.0\text{A}$ $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 175^{\circ}\text{C}$	- -	1.65 1.60	2.05 -	V
Gate-emitter threshold voltage	$V_{GE(th)}$	$I_C = 1.20\text{mA}, V_{CE} = V_{GE}$	4.1	4.9	5.7	V
Zero gate voltage collector current	$I_{CES}$	$V_{CE} = 600\text{V}, V_{GE} = 0\text{V}$ $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 175^{\circ}\text{C}$	- -	- 2500	40 -	$\mu\text{A}$
Gate-emitter leakage current	$I_{GES}$	$V_{CE} = 0\text{V}, V_{GE} = 20\text{V}$	-	-	100	nA
Transconductance	$g_{fs}$	$V_{CE} = 20\text{V}, I_C = 100.0\text{A}$	-	63.0	-	S
Integrated gate resistor	$r_G$			none		$\Omega$

Electrical Characteristic, at  $T_{vj} = 25^{\circ}\text{C}$ , unless otherwise specified

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
<b>Dynamic Characteristic</b>						
Input capacitance	$C_{ies}$	$V_{CE} = 25\text{V}, V_{GE} = 0\text{V}, f = 1\text{MHz}$	-	6230	-	pF
Output capacitance	$C_{oes}$		-	360	-	
Reverse transfer capacitance	$C_{res}$		-	175	-	
Gate charge	$Q_G$	$V_{CC} = 480\text{V}, I_C = 100.0\text{A},$ $V_{GE} = 15\text{V}$	-	610.0	-	nC
Internal emitter inductance measured 5mm (0.197 in.) from case	$L_E$		-	13.0	-	nH
Short circuit collector current Max. 1000 short circuits Time between short circuits: $\geq 1.0\text{s}$	$I_{C(SC)}$	$V_{GE} = 15.0\text{V}, V_{CC} \leq 400\text{V},$ $t_{SC} \leq 5\mu\text{s}$ $T_{vj} = 150^{\circ}\text{C}$	-	802	-	A

## Switching Characteristic, Inductive Load

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
<b>IGBT Characteristic, at <math>T_{vj} = 25^{\circ}\text{C}</math></b>						
Turn-on delay time	$t_{d(on)}$	$T_{vj} = 25^{\circ}\text{C},$ $V_{CC} = 400\text{V}, I_C = 100.0\text{A},$ $V_{GE} = 0.0/15.0\text{V},$ $R_{G(on)} = 3.6\Omega, R_{G(off)} = 3.6\Omega,$ $L\sigma = 63\text{nH}, C\sigma = 31\text{pF}$ $L\sigma, C\sigma$ from Fig. E Energy losses include "tail" and diode reverse recovery.	-	30	-	ns
Rise time	$t_r$		-	38	-	ns
Turn-off delay time	$t_{d(off)}$		-	290	-	ns
Fall time	$t_f$		-	31	-	ns
Turn-on energy	$E_{on}$		-	3.10	-	mJ
Turn-off energy	$E_{off}$		-	2.50	-	mJ
Total switching energy	$E_{ts}$		-	5.60	-	mJ

## TRENCHSTOP™ series

Diode Characteristic, at  $T_{vj} = 25^{\circ}\text{C}$ 

Diode reverse recovery time	$t_{rr}$	$T_{vj} = 25^{\circ}\text{C}$ , $V_R = 400\text{V}$ , $I_F = 100.0\text{A}$ , $di_F/dt = 1000\text{A}/\mu\text{s}$	-	230	-	ns
Diode reverse recovery charge	$Q_{rr}$		-	2.80	-	$\mu\text{C}$
Diode peak reverse recovery current	$I_{rrm}$		-	23.0	-	A
Diode peak rate of fall of reverse recovery current during $t_b$	$di_{rr}/dt$		-	-450	-	$\text{A}/\mu\text{s}$

## Switching Characteristic, Inductive Load

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	

IGBT Characteristic, at  $T_{vj} = 175^{\circ}\text{C}$ 

Turn-on delay time	$t_{d(on)}$	$T_{vj} = 175^{\circ}\text{C}$ , $V_{CC} = 400\text{V}$ , $I_C = 100.0\text{A}$ , $V_{GE} = 0.0/15.0\text{V}$ , $R_{G(on)} = 3.6\Omega$ , $R_{G(off)} = 3.6\Omega$ , $L\sigma = 63\text{nH}$ , $C\sigma = 31\text{pF}$ $L\sigma$ , $C\sigma$ from Fig. E Energy losses include "tail" and diode reverse recovery.	-	31	-	ns
Rise time	$t_r$		-	52	-	ns
Turn-off delay time	$t_{d(off)}$		-	351	-	ns
Fall time	$t_f$		-	42	-	ns
Turn-on energy	$E_{on}$		-	6.00	-	mJ
Turn-off energy	$E_{off}$		-	3.70	-	mJ
Total switching energy	$E_{ts}$		-	9.70	-	mJ

Diode Characteristic, at  $T_{vj} = 175^{\circ}\text{C}$ 

Diode reverse recovery time	$t_{rr}$	$T_{vj} = 175^{\circ}\text{C}$ , $V_R = 400\text{V}$ , $I_F = 100.0\text{A}$ , $di_F/dt = 1000\text{A}/\mu\text{s}$	-	328	-	ns
Diode reverse recovery charge	$Q_{rr}$		-	8.70	-	$\mu\text{C}$
Diode peak reverse recovery current	$I_{rrm}$		-	48.0	-	A
Diode peak rate of fall of reverse recovery current during $t_b$	$di_{rr}/dt$		-	-847	-	$\text{A}/\mu\text{s}$

TRENCHSTOP™ series

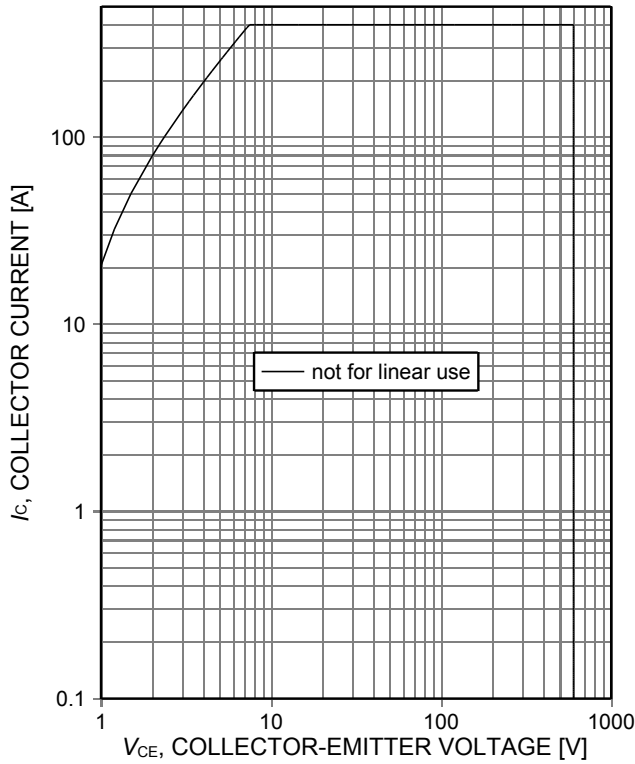


Figure 1. **Safe operating area**  
 ( $D=0$ ,  $T_C=25^\circ\text{C}$ ,  $T_J\leq 175^\circ\text{C}$ ,  $V_{GE}=0/15\text{V}$ ,  $t_p=1\mu\text{s}$ )

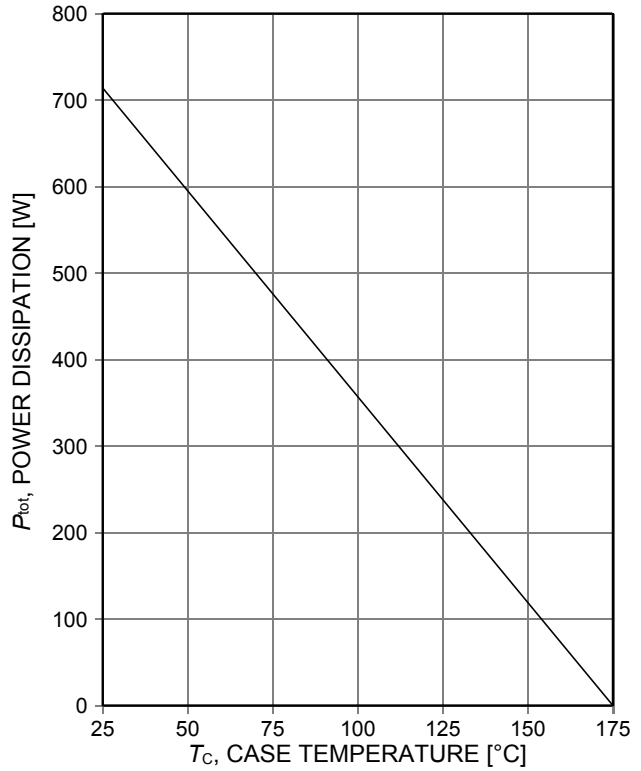


Figure 2. **Power dissipation as a function of case temperature**  
 ( $T_J\leq 175^\circ\text{C}$ )

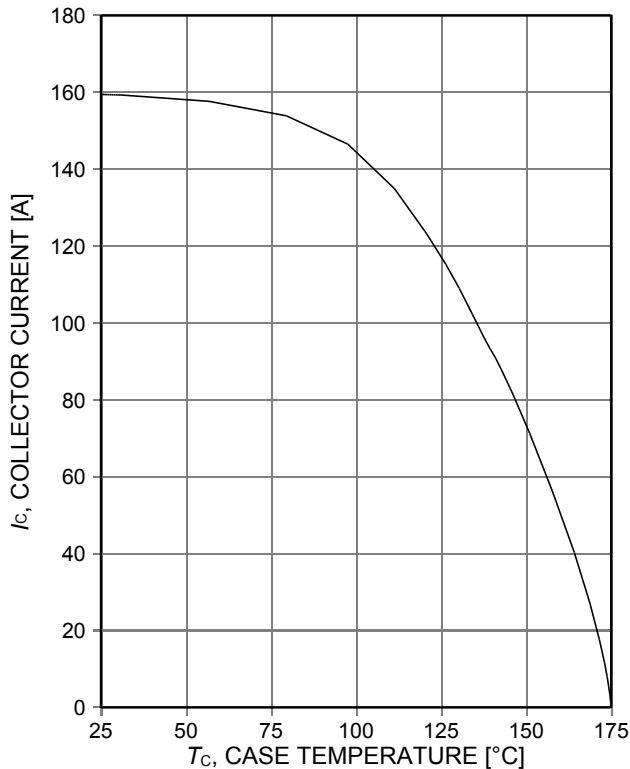


Figure 3. **Collector current as a function of case temperature**  
 ( $V_{GE}\geq 15\text{V}$ ,  $T_J\leq 175^\circ\text{C}$ )

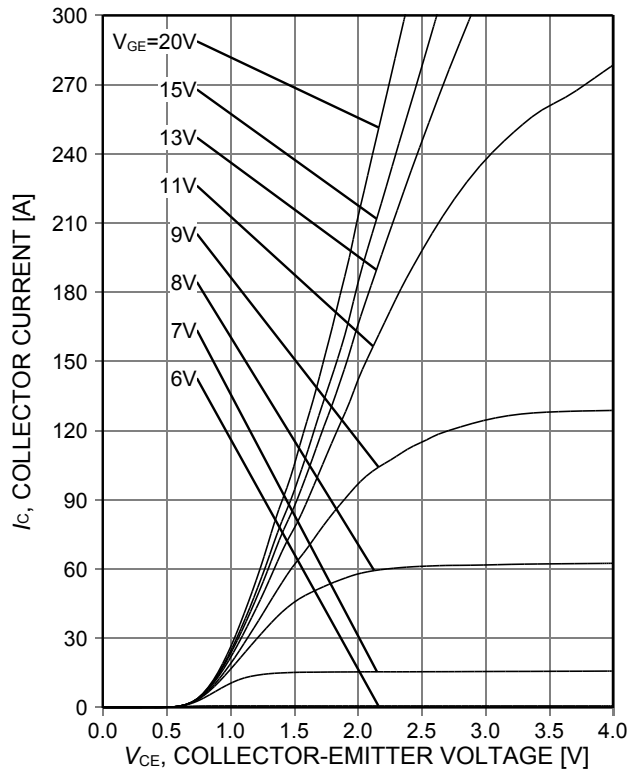


Figure 4. **Typical output characteristic**  
 ( $T_J=25^\circ\text{C}$ )

TRENCHSTOP™ series

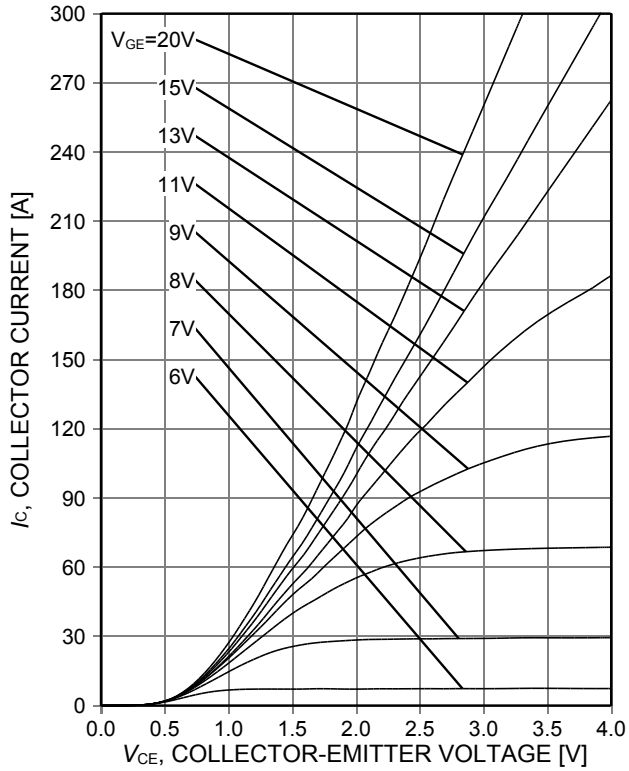


Figure 5. Typical output characteristic ( $T_j=175^\circ\text{C}$ )

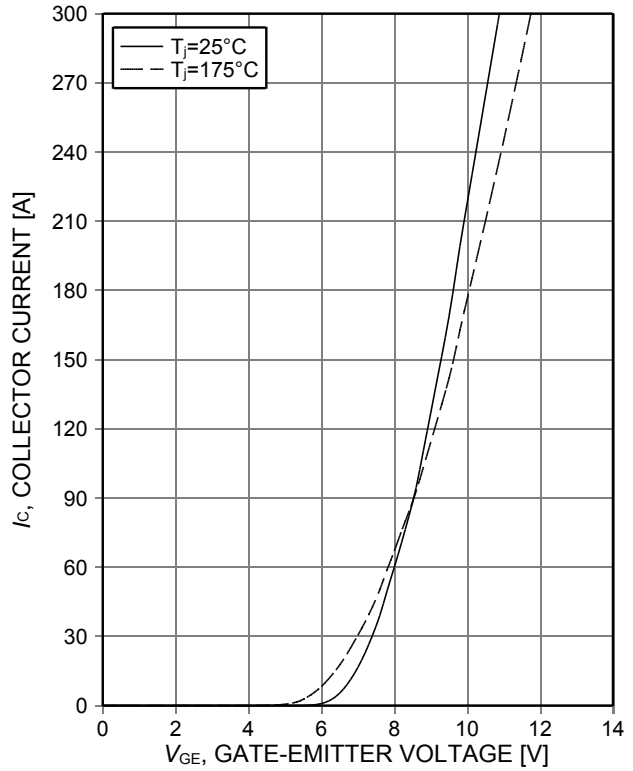


Figure 6. Typical transfer characteristic ( $V_{CE}=20\text{V}$ )

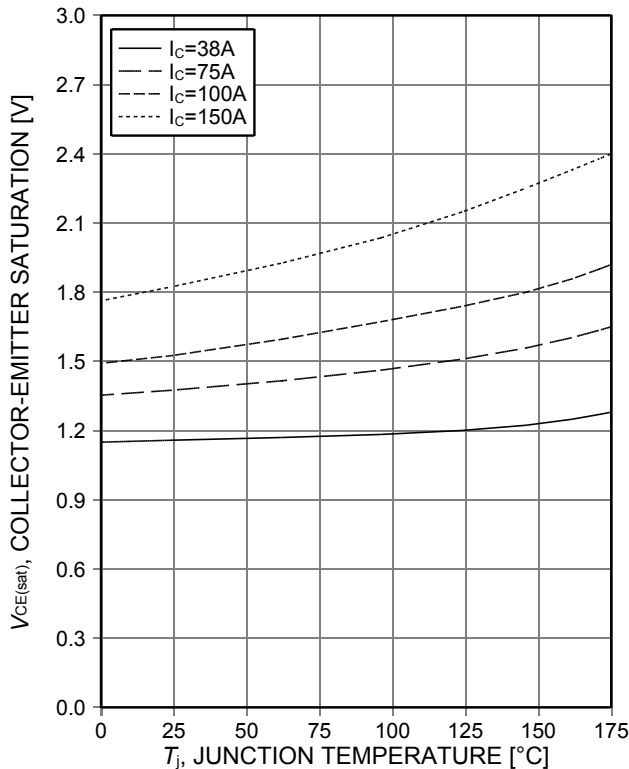


Figure 7. Typical collector-emitter saturation voltage as a function of junction temperature ( $V_{GE}=15\text{V}$ )

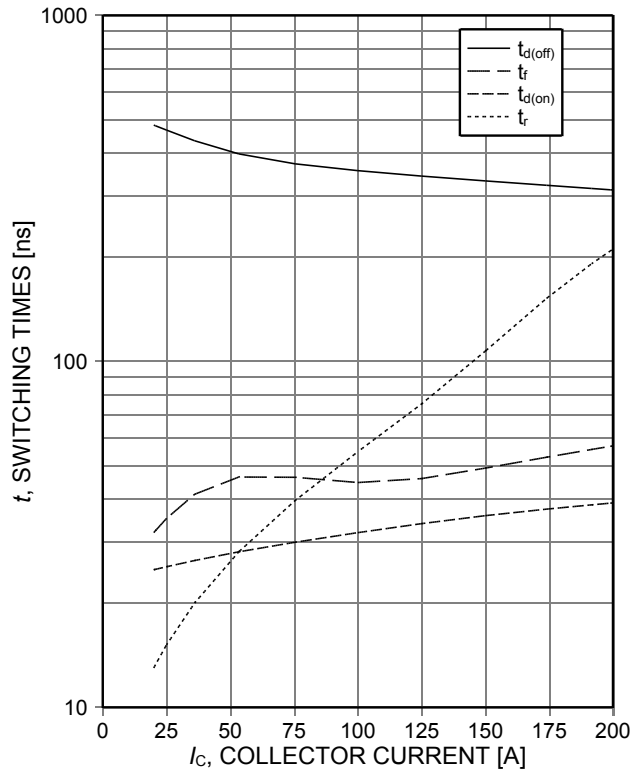


Figure 8. Typical switching times as a function of collector current (inductive load,  $T_j=175^\circ\text{C}$ ,  $V_{CE}=400\text{V}$ ,  $V_{GE}=15/0\text{V}$ ,  $r_G=3,6\Omega$ , Dynamic test circuit in Figure E)

TRENCHSTOP™ series

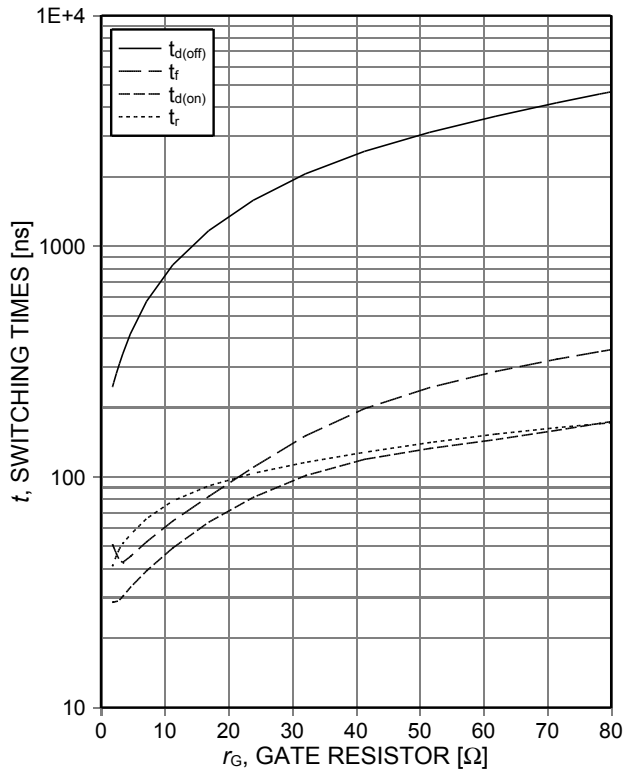


Figure 9. Typical switching times as a function of gate resistor (inductive load,  $T_j=175^\circ\text{C}$ ,  $V_{CE}=400\text{V}$ ,  $V_{GE}=15/0\text{V}$ ,  $I_C=100\text{A}$ , Dynamic test circuit in Figure E)

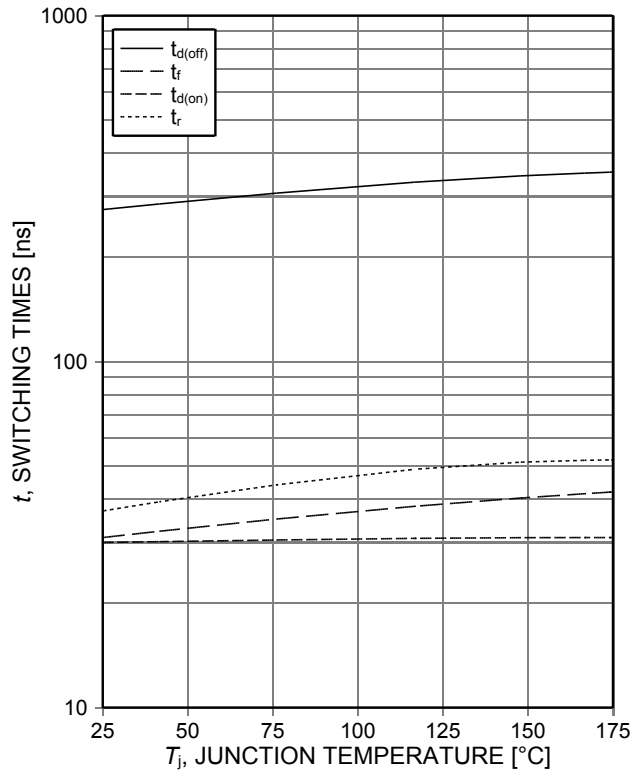


Figure 10. Typical switching times as a function of junction temperature (inductive load,  $V_{CE}=400\text{V}$ ,  $V_{GE}=15/0\text{V}$ ,  $I_C=100\text{A}$ ,  $r_G=3,6\Omega$ , Dynamic test circuit in Figure E)

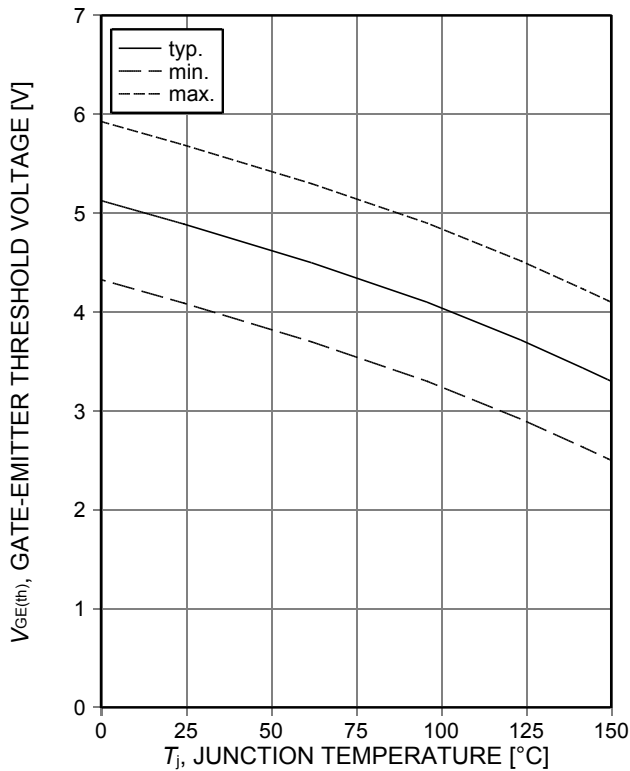


Figure 11. Gate-emitter threshold voltage as a function of junction temperature ( $I_C=1.2\text{mA}$ )

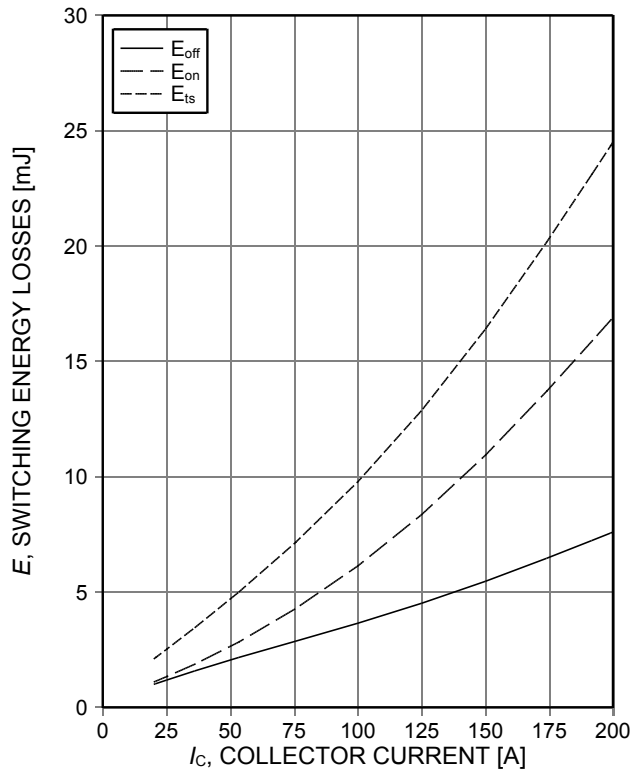


Figure 12. Typical switching energy losses as a function of collector current (inductive load,  $T_j=175^\circ\text{C}$ ,  $V_{CE}=400\text{V}$ ,  $V_{GE}=15/0\text{V}$ ,  $r_G=3,6\Omega$ , Dynamic test circuit in Figure E)



TRENCHSTOP™ series

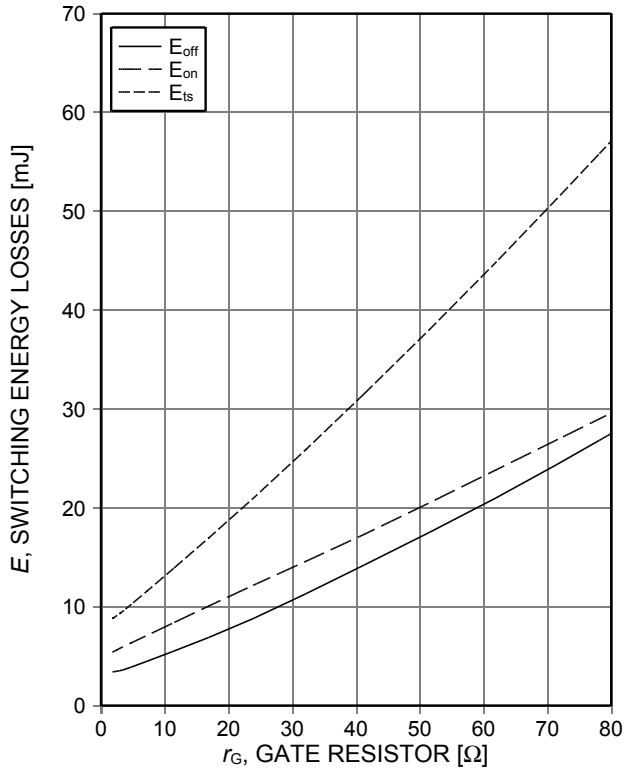


Figure 13. **Typical switching energy losses as a function of gate resistor**  
 (inductive load,  $T_j=175^\circ\text{C}$ ,  $V_{CE}=400\text{V}$ ,  $V_{GE}=15/0\text{V}$ ,  $I_C=100\text{A}$ , Dynamic test circuit in Figure E)

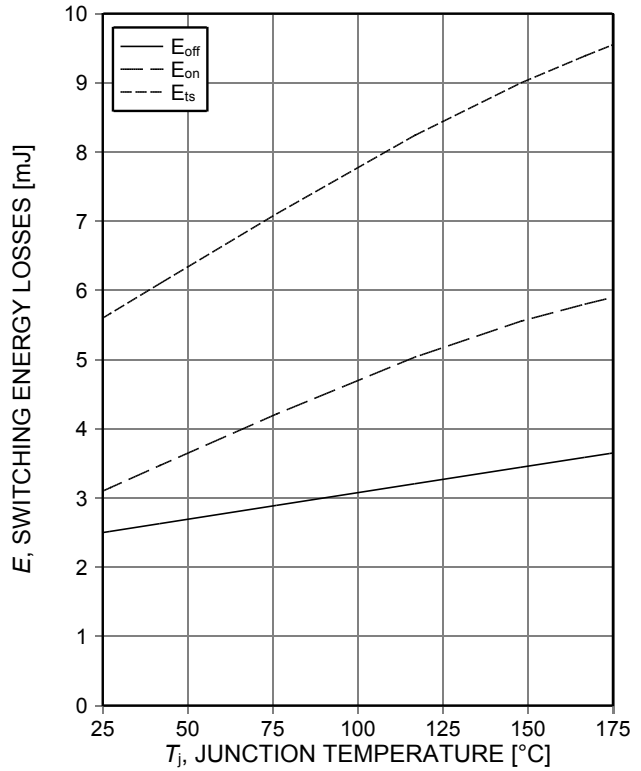


Figure 14. **Typical switching energy losses as a function of junction temperature**  
 (inductive load,  $V_{CE}=400\text{V}$ ,  $V_{GE}=15/0\text{V}$ ,  $I_C=100\text{A}$ ,  $r_G=3,6\Omega$ , Dynamic test circuit in Figure E)

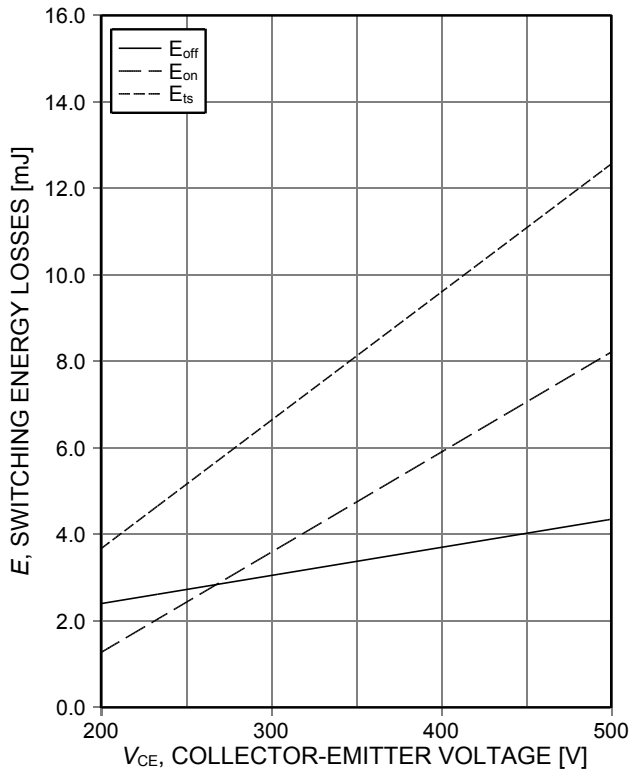


Figure 15. **Typical switching energy losses as a function of collector emitter voltage**  
 (inductive load,  $T_j=175^\circ\text{C}$ ,  $V_{GE}=15/0\text{V}$ ,  $I_C=100\text{A}$ ,  $R_G=3,6\Omega$ , Dynamic test circuit in Figure E)

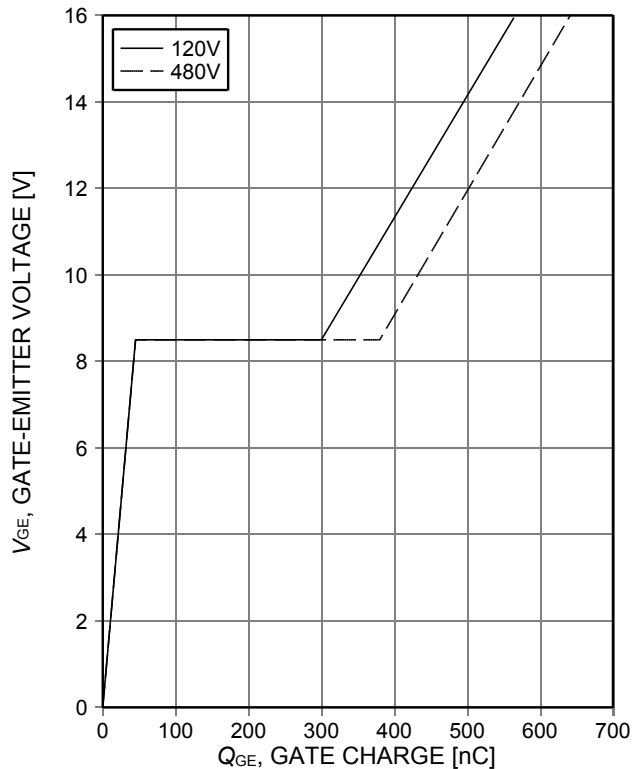


Figure 16. **Typical gate charge**  
 ( $I_C=100\text{A}$ )

TRENCHSTOP™ series

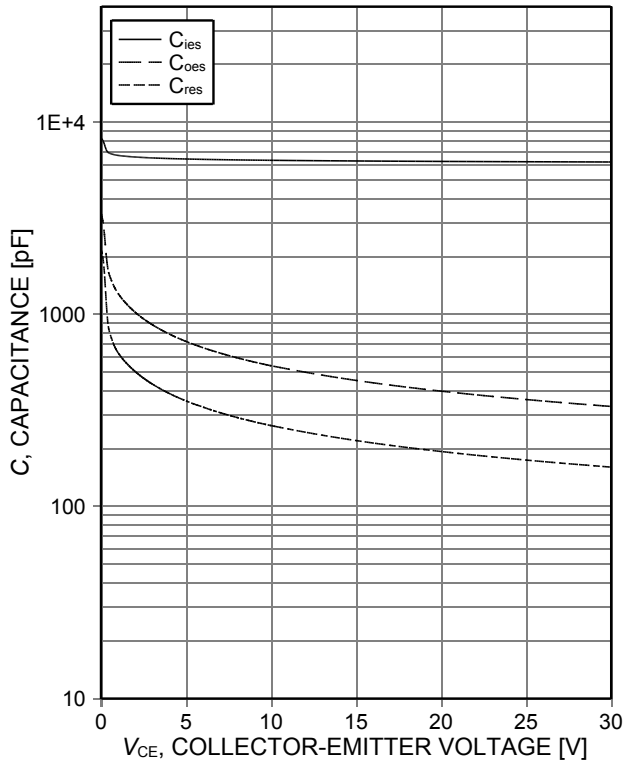


Figure 17. Typical capacitance as a function of collector-emitter voltage ( $V_{GE}=0V$ ,  $f=1MHz$ )

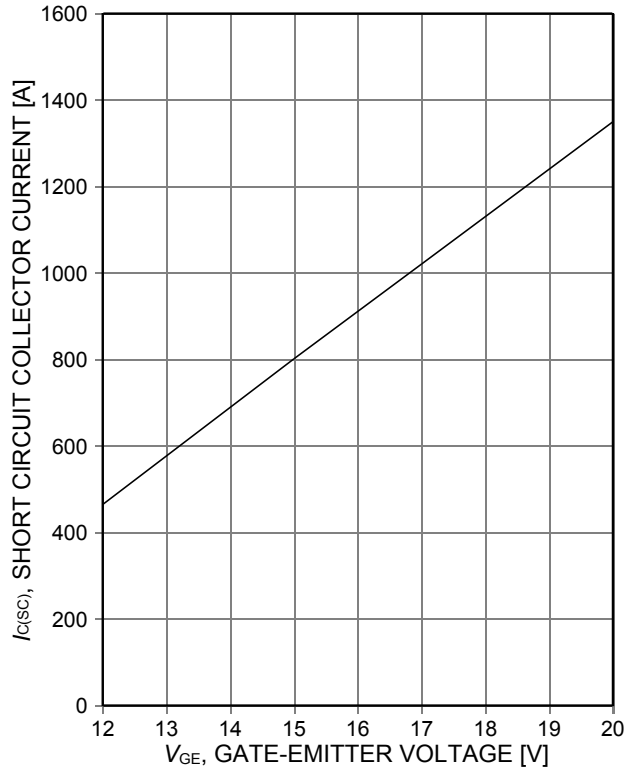


Figure 18. Typical short circuit collector current as a function of gate-emitter voltage ( $V_{CE}\leq 400V$ ,  $T_j\leq 150^\circ C$ )

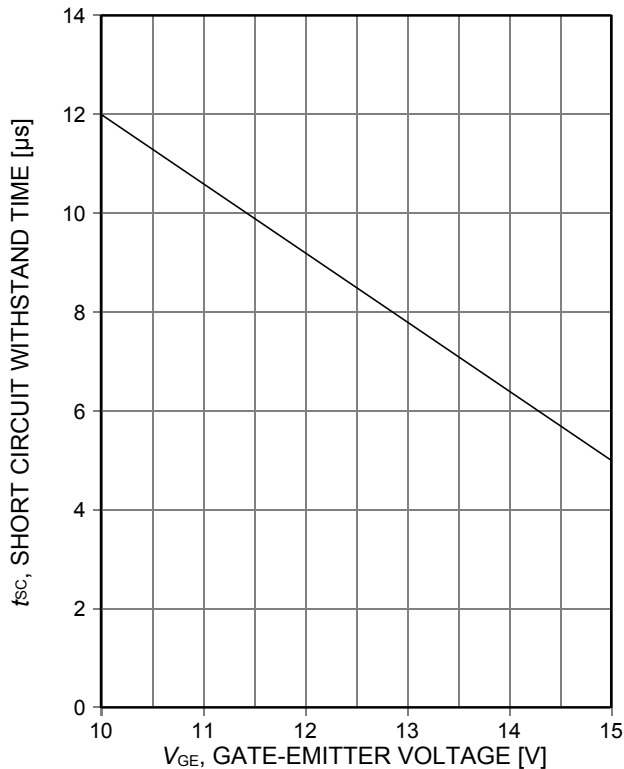


Figure 19. Short circuit withstand time as a function of gate-emitter voltage ( $V_{CE}=400V$ , start at  $T_j=25^\circ C$ ,  $T_{jmax}\leq 150^\circ C$ )

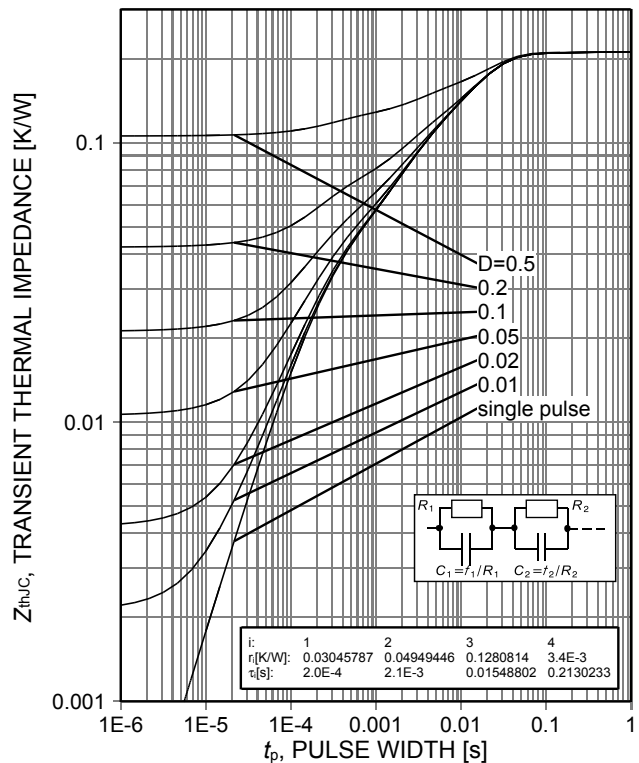


Figure 20. IGBT transient thermal impedance as a function of pulse width for different duty cycles  $D$  ( $D=t_p/T$ )

TRENCHSTOP™ series

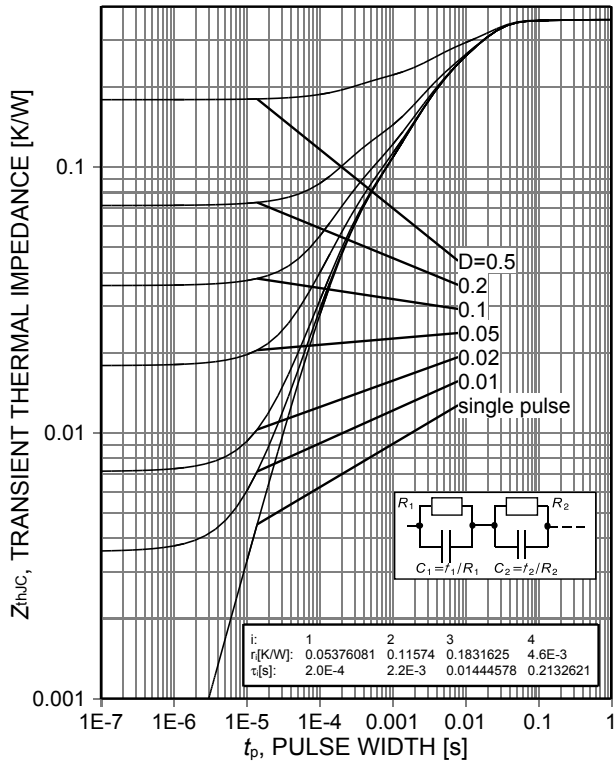


Figure 21. Diode transient thermal impedance as a function of pulse width for different duty cycles  $D$  ( $D=t_p/T$ )

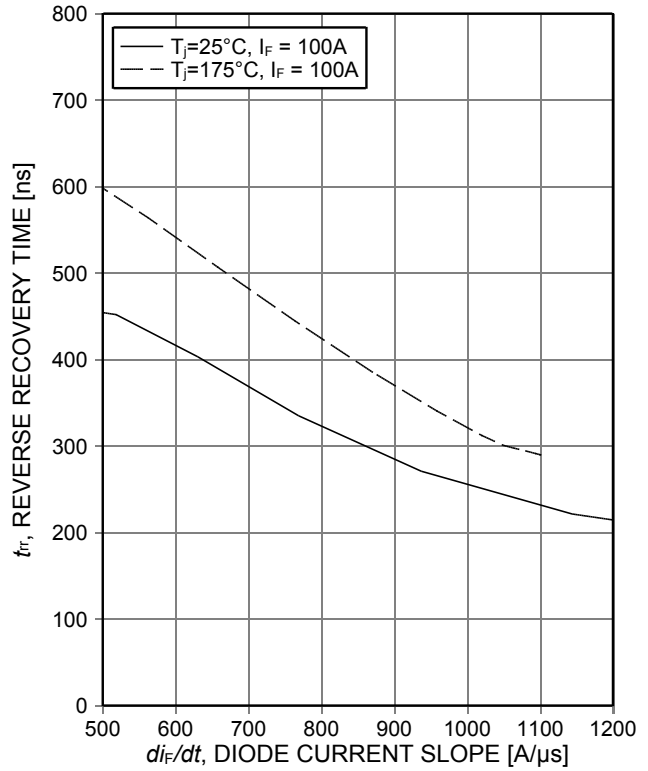


Figure 22. Typical reverse recovery time as a function of diode current slope ( $V_R=400V$ , Dynamic test circuit in Figure E)

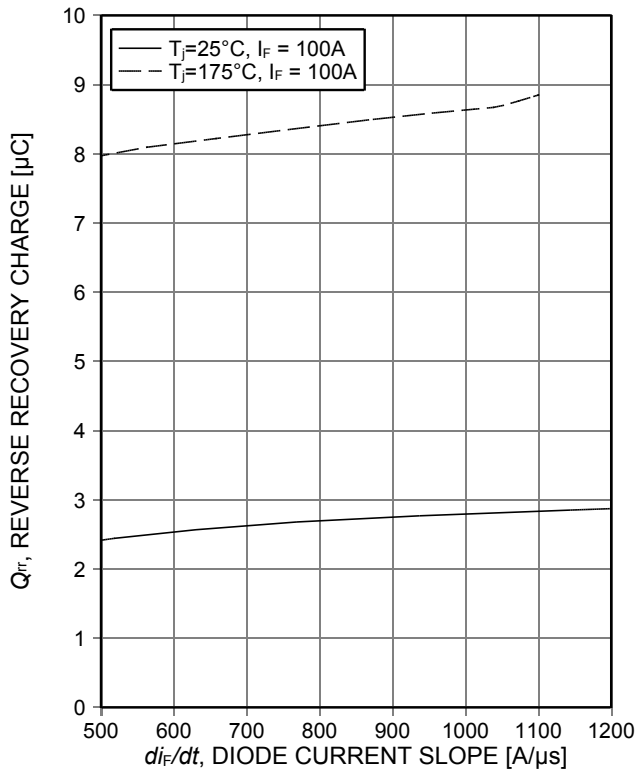


Figure 23. Typical reverse recovery charge as a function of diode current slope ( $V_R=400V$ , Dynamic test circuit in Figure E)

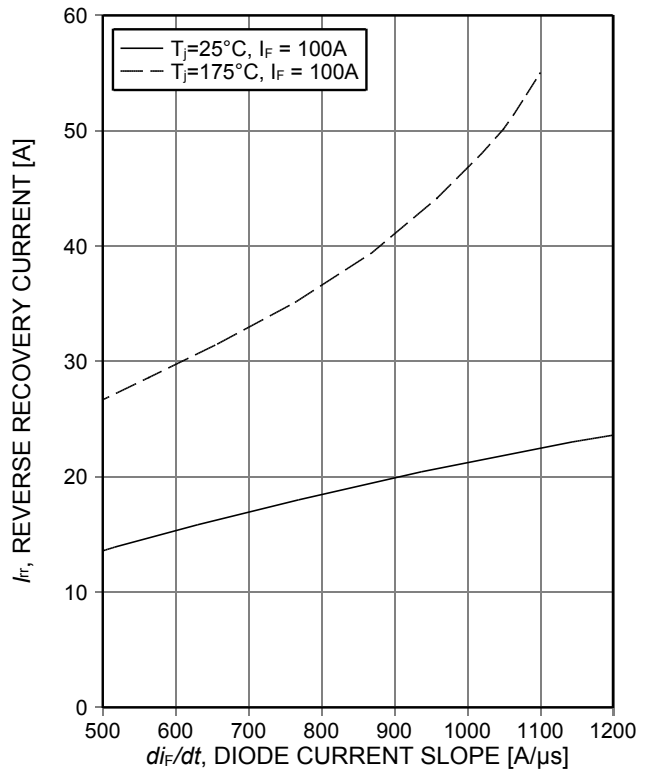


Figure 24. Typical reverse recovery current as a function of diode current slope ( $V_R=400V$ , Dynamic test circuit in Figure E)

TRENCHSTOP™ series

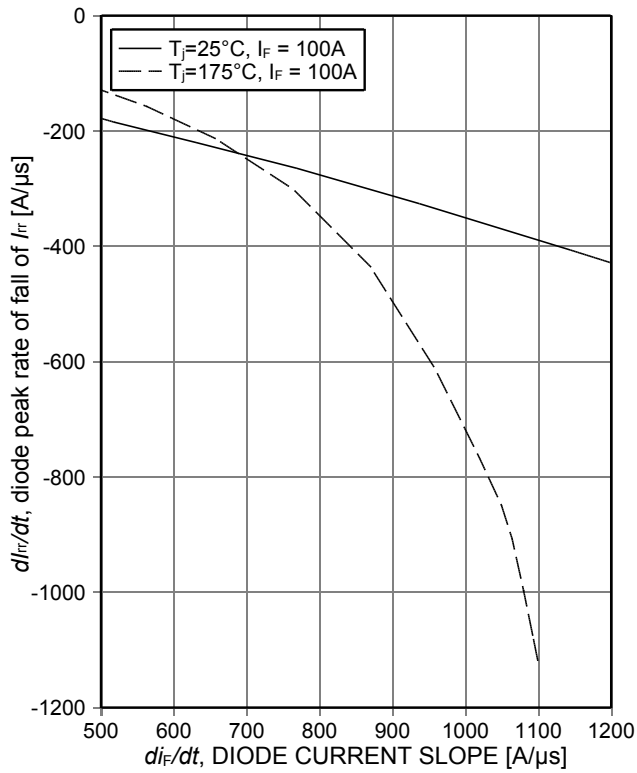


Figure 25. **Typical diode peak rate of fall of reverse recovery current as a function of diode current slope**  
( $V_R=400V$ , Dynamic test circuit in Figure E)

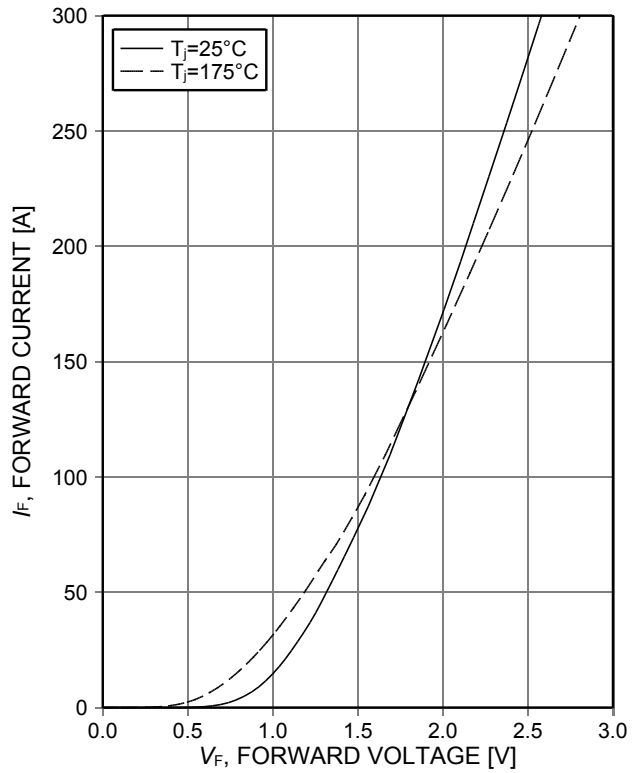


Figure 26. **Typical diode forward current as a function of forward voltage**

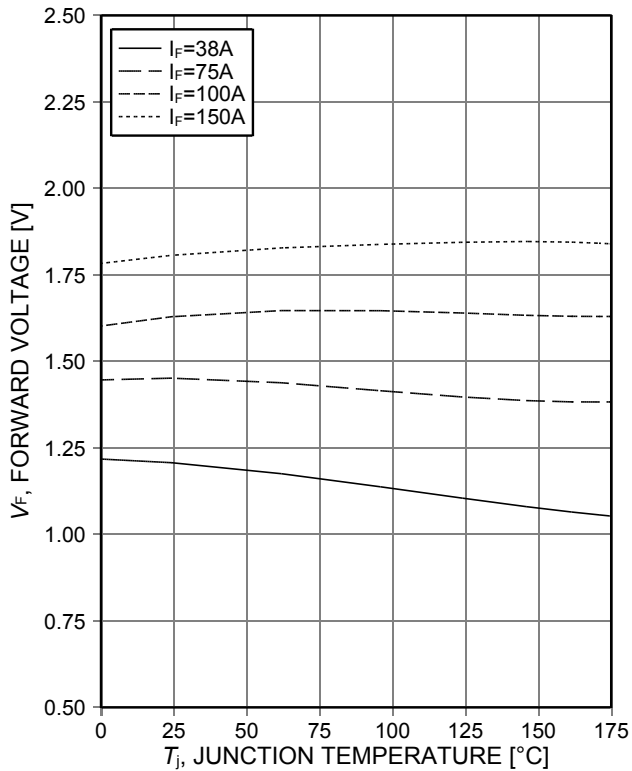
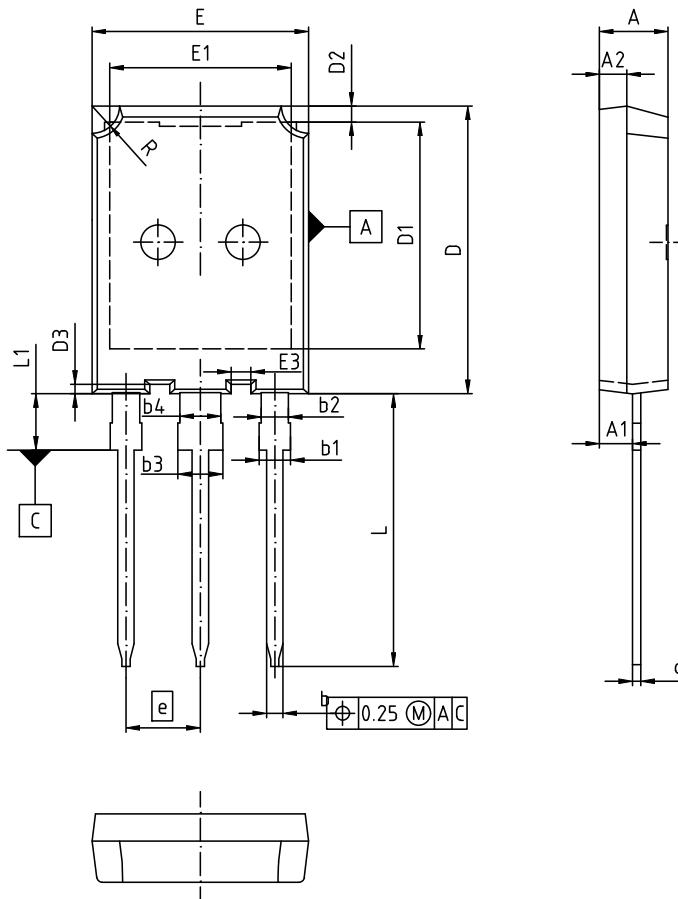


Figure 27. **Typical diode forward voltage as a function of junction temperature**

Package Drawing PG-TO247-3-46



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.90	5.10	0.193	0.201
A1	2.31	2.51	0.091	0.099
A2	1.90	2.10	0.075	0.083
b	1.16	1.26	0.046	0.050
b1	1.96	2.25	0.077	0.089
b2	1.96	2.06	0.077	0.081
c	0.59	0.66	0.023	0.026
D	20.90	21.10	0.823	0.831
D1	16.25	16.85	0.640	0.663
D2	1.05	1.35	0.041	0.053
D3	0.58	0.78	0.023	0.031
E	15.70	15.90	0.618	0.626
E1	13.10	13.50	0.516	0.531
E3	1.35	1.55	0.053	0.061
e	5.44 (BSC)		0.214 (BSC)	
N	3		3	
L	19.80	20.10	0.780	0.791
L1	-	4.30	-	0.169
R	1.90	2.10	0.075	0.083

DOCUMENT NO.  
Z8B00174295

SCALE

EUROPEAN PROJECTION

ISSUE DATE  
13-08-2014

REVISION  
01

Testing Conditions



Figure A. Definition of switching times

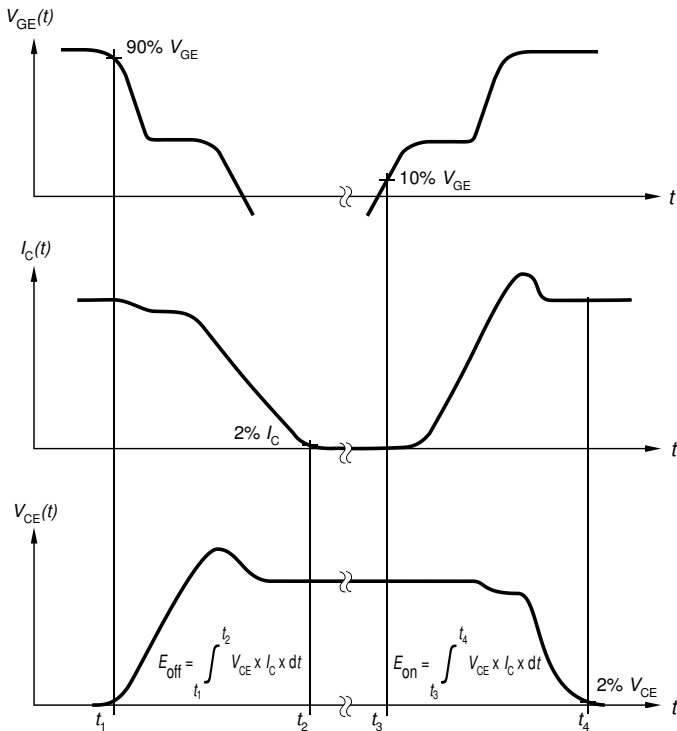


Figure B. Definition of switching losses

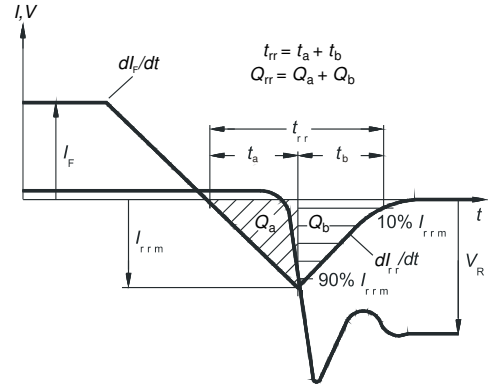


Figure C. Definition of diode switching characteristics

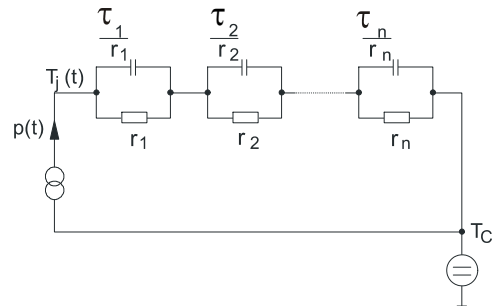


Figure D. Thermal equivalent circuit

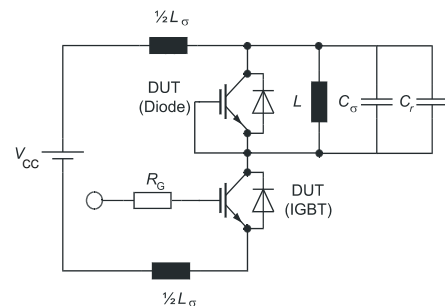


Figure E. Dynamic test circuit  
Parasitic inductance  $L_{\sigma}$ ,  
parasitic capacitor  $C_{\sigma}$ ,  
relief capacitor  $C_r$ ,  
(only for ZVT switching)

**Revision History**

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IKQ100N60T

**Revision: 2017-11-15, Rev. 2.3**

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Previous Revision

Revision	Date	Subjects (major changes since last revision)
2.1	2014-11-03	Final data sheet
2.2	2014-11-18	Update of Transconductance gfs
2.3	2017-11-15	Minor change Fig. 20 and Fig. 21

## Trademarks

All referenced product or service names and trademarks are the property of their respective owners.

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